





Classical Electronics to Control Qubits and Correct Errors in Room-temperature and Cryogenic Environments

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Project Manager of Moonshot Goal 6

https://www.greenlab.kit.ac.jp/qubecs/



Keynote at Quest 2024 in Kyushu

Agenda

Self Introduction

Introduction



✓Moonshot Goal 6 for quantum computers

Integrated circuits (Classical electronics) and quantum computers

QUBECS

Overview of my project for developing an FTQC (Fault-tolerant quantum computer)

Conclusion



Prof. Kazutoshi Kobayashi

- Graduated from Kyoto University, 1991 (BE), 1993 (ME). Ph. D in 1999
 - One of mentors was Prof. Yasuura (Former vice president of Kyushu Univ.) as same as Prof. Koji Inoue
- Research Topics: CiM (Computing in Memory) for Ph. D thesis, system-level design (SystemC), variation-aware FPGA, reliability issues (soft error and aging degradation), power electronics and etc.

One of the most famous professors in the field of semiconductor reliability in Japan

 From 2022, Project Manager of the Moonshot goal 6 for FTQC (Fault-tolerant quantum computer)





Prof. Yasuura and Prof. Inoue

My Research History

Computing in Memory (CiM) (1991-2000)



SIMD-type Control

broadcast/listen

Our Research Group at KIT: VLSI System

http://www-vlsi.es.kit.ac.jp/



 7 faculty members: 2 full profs, 2 assoc. profs, 2 project assoc. profs and 1 project assistant prof.





Kobayashi

Hiroki

Shintani

Tanaka Navarro

Furuta Assoc. prof. in Okayama Pref. Univ from 2024

✓ Biggest group in KIT

Takai

- ✓ Prof. Takai and Shintani joined in 2022
- ✓ Prof. Tanaka, Navarro, Takayama joined in 2024
- ✓ 3 Ph.D. candidates, 30 master-course students, 14 undergraduates



Takayama

Everyone Goes to Quantum Computers ^^;

Prof. Edoardo Charbon from EPFL

- His first paper on IEEE Xplore was "Single Photon Imaging in CMOS" in 2006
- He knows Prof. Onodera (my boss in Kyoto University)
- Dr. Kristiaan De Greve from imec
 - His first paper on IEEE Xplore was "Fault-tolerant quantum repeaters for long-distance quantum communication based on quantum dots" in 2012
- Prof. Tibor Grasser from TU Wien (Famous in aging degradation on a chip)
 - ✓ He sent me an e-mail "We have entered this field a little while ago and are working on DFT calculations of SiGe spin qubits"



Prof. Charbon Prof. Onodera/Yasuura



At imec



Prof. Grasser

Governmental Funds and Projects to Support QC

 Q-LEAP (Quantum Leap Flagship Program) 2018-2028 https://www.q-leap.org/



- ✓ Deal with broad area of quantum technology including quantum computers
- Prof. Nakamura (Riken) and Prof. Fujii (Osaka-U) are project leaders of hardware and software
- Q-STAR (Quantum STrategic industry Alliance for Revolution) 2021 https://qstar.jp/
 - Accelerates the shift to quantum technology through industry-government-academia collaboration
 - ✓ 17 Special member companies: KYOCERA, Canon, NEC, Hitachi, Fujitsu, Fixstar, Toyota and etc. Many corporate and start-up members

• Moonshot Goal 6, 2020-2030 https://www.jst.go.jp/moonshot/en/program/goal6/

Only focus on FTQC

Moonshot Goal 6 "Realization of a fault-tolerant universal quantum computer that will revolutionize economy, industry, and security by 2050." List of Project Managers



Program Director Prof. Kitagawa (QIQB, Osaka-U,)

• 2020-2030

- Kobayashi joined in 2022
- 12 project managers (PMs)
- Total Budget is 30B JPY (200M USD)



PIs of MS6: Prof. Fujii, Prof. Tanaka, Dr. Tabuchi etc..

Current & Future Quantum Computers



Quantum Computer "Ei" at Riken

64 Qubits without error correction

Fault Tolerant Quantum Computer

> 1,000,000 Qubits with error correction

Requirement for FTQC

• Fidelity (error rate) and variation of Qubit

- Current error rate of superconducting qubits is around > 1e-2 (1%)
 - Early FTQC with 1e4 physical qubits requires 1e-4 error rate [arXiv:2303.13181]
 - True FTQC must have less than 1e-5 error rates. Very hard barrier to establish superconducting qubit with 1e-5 error rate. We must assume 1e-4 error rate for true FTQC (by Prof. Kitagawa from Osaka U.)
 - > Huge variation of qubit \rightarrow fine/delicate control
 - Similar to the early days of semiconductor chips
 - $\square \quad Ge (GeO_2 \text{ is water-soluble}) \rightarrow Si (SiO_2 \text{ is dielectric})$

• Latency and code cycle of error correction

- ✓ Less than 10us. 500 ns code cycle (1/1000 of T1 or T2)
- Ultra low power operation for scalable qubit control over

1,000 qubit in a fridge

✓ 1W/1,000qubit=1mW/qubit

0	Cooling Power	
	30W	50K
Cooling power of fridge.	1-1.5W	4K

or vacuum tube?



Ge point contact transistor in 1940's





[DOI: 10.1557/mrs.2013.229]

Fidelity and Scalability of Superconducting Qubits

- Superconducting qubit is a mechanical oscillator.
 - ✓ Josephson Junction (JJ) works as a nonlinear inductive element (L_J+C_J)
 - ✓ JJ is an insulator (Al_2O_3 amorphous)
- Si can be formed as "Perfect Crystal" (Similar to Diamond)
 - ✓ Si is a gift to form semiconductor chips w/ high fidelity (<10⁻¹⁵)
 - ✓ SiO₂ has many defects to cause noise and degradations (RTN and BTI)

RTN and BTI are within my expertise

"The most widespread and robust process for fabricating JJ involves the diffusion-limited oxidation of an aluminum base layer to form a relatively uniform amorphous oxide tunnel barrier." [M. Gurvitch et. al., Appl. Phys. Lett. 42, 472 (1983).]





Cross section of MOS transistor

Recent Advances of Si-based Semiconductor Chips

- "The 7nm process chip has no 7nm dimension." by Prof. Hiramoto
- Wavelength of EUV (Extremely ultra-violet) exposure is 13.5 nm
- 7nm, 5nm, 3nm are just code names

Cell height

✓ Integrated density of transistors are increased to minimize cell height



https://www.angstronomics.com/p/the-truth-of-tsmc-5nm



From IRDS (International roadmap for devices and systems): Gate pitch = CPP



Future of Semiconductor chips & Quantum Computers

- Moore's Law: Gordon Moore predicted that the number of transistors on an integrated circuit will double every two years with minimal rise in cost
 - Recent advances come from high-cost production method like "EUV" and etc.

• Power and prices/tr are incredibly increased!

- ✓ iPhone 5: \$199 (2012) vs iPhone 15 Plus: \$899 (2023) Computer resources for AI consumes huge power
 - > Neuman computers equivalent to a human brain will consume 2.4 BW (= 3 atomic power plants)
- ✓ Rapidus (2nm fab in Hokkaido, Japan) will consume 10% electric power in Hokkaido.
- Quantum computer may be a help for power crisis for AI and power-hungry applications



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Agenda

Self Introduction

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- ✓Moonshot Goal 6 for quantum computers
- Integrated circuits (Classical electronics) and quantum computers

QUBECS

Overview of my project for developing an FTQC (Fault-tolerant quantum computer)

Conclusion



QUBECS: Quantum Bit Error Correction System

• Acronym of my project

 Officially entitled "Development of Scalable Highly Integrated Quantum Bit Error Correction System"

To develop Fault-Tolerant Quantum Computer (FTQC)

- ✓ Our target is above qubits.
- Classical electronics (integrated circuits, semiconductor chips) and sand going to be used to control semiconductor (+a) qubits and correct errors.

• Two key persons

- ✓ Dr. Sano: Advisor of Moonshot Goal 6
- ✓ Dr. Miyoshi: Developing qubit controllers with Riken and Osaka U.





Moonshot Goal 6 "Quantum computer" by Kobayashi PM

Our Goals in 2025 and 2030

• 2025

 ✓ Develop a prototype system for FTQC with ~100 physical qubits

• 2030

 Develop a system for FTQC scalable up to 1M physical qubits



2025: Prototype system for FTQC with ~100 physical qubits



2030: System for FTQC scalable up to 1,000,000 physical qubits

Principal Investigators

*: Subject Leader







Dr. Sano* (RIKEN)

Prof. Kadomoto Prof. Osana (U. Tokyo) (Kumamoto U.)

Subject 1: Backend for error correction



Dr. Miyoshi*

(Quel-inc)

Subject 2: Advanced Qubit **Control Frontend**



Quel-1: Qubit controller







Prof. Shintani (KIT)

Prof. Sato (Kyoto U.)

Subject 3: Scalable Classical-Quantum Interface by Photonic/Cryo-CMOS Integrated Circuits





Mr. Igarashi* (Socionext)

Subject 5: Frontend RF LSI at room temperature





Prof. Kobayashi Prof. Tsuchiya (Shiga PU) (KIT)



(KIT)



(KEK)



(Meiji U)



Prof. Kishida (Toyama PU)

Subject 4: Cryo CMOS ASICs for Frontend/backend

14 PIs with 153 researchers of qubit-controllers, computer architectures and IC

Relationship among All Subjects



Cryogenic: extremely cold



Challenges of Our Project

- Subject 1 & 2: Scalable error correction system
 - ✓ How to correct errors of millions of physical qubits
 - Low-latency network among distributed quantum error correction systems
- Subject 2 & 5: Accurate but low-power qubit controller at room temp.
 - ✓ Ensure accuracy for current superconducting qubit with huge variation and low fidelity
 - ✓ Low-power SoC to control qubits at room temp.
 - ✓ Universal qubit controller for any qubit
- Subject 1 & 2 & 3 & 4: Scalable qubit control and error correction at cryo. temp.
 - Ultra Low-power SoC to control qubits at cryo. temp. including digital/analog/RF building blocks
 - ✓ Simplified qubit control method for future stable qubits with higher fidelity
 - ✓ Optical interface between cryo. and room temp. to reduce # of wires and heat dissipation

Selection of Process Technology

• Subject 3 & 4 : TSMC 22nm Bulk

- Cheapest transistor cost
 - > 7M JPY / 2mmx3mm chip (Up to 100M Tr /chip, 7 JPY/Tr)
- ✓ Short TAT (Chip delivery after 70 days of tapeout)
- Difficult to design

Subject 5: GlobalFoundries 22 nm FDSOI

- ✓ Lower noise and power than 22 nm bulk
- ✓ More expensive than bulk







Subject 1: Backend for Error Correction

Theme 1: Scalable backend system for error correction by Dr. Sano Theme 2: ASIC implementation of QEC cores by Prof. Kadomoto Theme 3: Dependable error correction backend by Prof. Osana



Subject 1 (Backend for error correction): Goal

Goal

- ✓ QEC Backend system with scalable HW algorithm
- ✓ Feasibility of backend system scalable to 1000 logical qubits for their QEC and operation

Milestones

- Develop QEC algorithm and HW design considering performance required by frontend (latency, throughput)
- ✓ Demonstrate QEC backend system with FPGAs for 1 logical qubit with 100 physical qubits (d=7 ~ 11)

Organization

- Theme 1HW-oriented QEC algorithm and
backend system with FPGAs[Sano]
- Theme 2 Error correction algorithm for ASIC [Kadomoto]
- Theme 3 Dependable backend for QEC



System organization of FTQC

[Osana]

Moonshot Goal 6 "Quantum computer" by Kobayashi PM

Backend for Error Correction

- Goal Establish QEC algorithm and its dedicated hardware design for high-throughput, low-latency, and scalable backend system
- Sub themes and progress

1) Algorithm and hardware for QEC decoder

- Syndrome subgraph decoder
- Hardware design and software simulator
- FPGA prototype

2) FPGA cluster for backend system

- Requirement and specification for FPGAs
- Procurement process will start soon.

3) Interface and system architecture

Network with frontend units (together with Theme 3)



Theme 1: Backend system with FPGAs

Sano

2024/7/2-4

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FPGA Cluster for QEC Backend

• Requirement and specification for FPGA

- ✓ High-end and large-scale FPGA, fabricated in state-of-the-art CMOS technology
- ✓ HBM2 memory with high bandwidth
- ✓ 400Gbps port for high-speed network
- ✓ PCIe Gen5 x8 or 16 for fast communication with CPU
- ✓ MCIO port for extension (e.g., ASICs)
- ✓ OFS (Open FPGA Stack) support
- New FPGA board will be delivered
 GSEFP- DD (1)

soon

✓ A 32-FPGAs Cluster will be available



Example of FPGA cards to satisfy the requirement

Dependable Error Correction Backend

- Goal Achieve highly-reliable FPGA cluster and its interconnect for error correction backend
- Sub-themes and progress

1) Ethernet-based scalable interconnect (latency: mid-high)

- Portable 100Gbit Ethernet controller for the current and upcoming frontend and backend FPGAs
- Frontend emulator for operation test of backend cluster
- > Dependable transport over Ethernet (similar to RoCE), with high-level flow control in progress

2) Ultra-low latency interconnect

- > 100G point-to-point transport within 100ns
- 100G simultaneous multi-point interconnect implementation and proof-of-concept test in progress

3) System-level dependability

Portable SEU mitigation framework development in progress (e.g., Correction of config registers in FPGAs)







Theme 3: Interconnect and system-level dependability

1) Ethernet-based Scalable Interconnect

Portable Ethernet controller for BE/FE FPGAs

Implementation and basic tests are done, will be integrated to RIKEN FPGA cluster

• Advanced flow control=Lossless ethernet on FPGAs

- ✓ Used in RoCE: RDMA over Converged Ethernet
- ✓ Built a Linux-based RoCE test system
 - Intensive packet analysis is done
 - > Working on FPGA implementation (in UDP like RoCE)
 - > This will help large-scale FPGA clusters in near future
- FEU emulator for QEC backend test / demo
 - ✓ 16 FEUs for d=5, 36 FEUs for d=11
 - ✓ Emulator with 36 10GbE ports is now ready
 - ✓ Will be available in Aug



Emulate 4 FEUs per port

2) Ultra-Low Latency Interconnect

- Ethernet latency is too large
 - ✓ End-to-end latency > 1μ s

• P2P protocols are better in latency

- ✓ Proprietary Aurora / SL3 has latency < 400us.
- ✓ Our Kyokko core has latency < 100us.</p>
- But it's point-to-point: can't connect multiple FPGAs

Multipoint extension

- ✓ Signal distributor board + extended P2P protocol
- Enables to connect multiple FEUs + backend FPGAs
- Distributor board for Proof-of-concept test is under development









Subject 2: Advanced Qubit Control Frontend

By Dr. Miyoshi



Dr. Miyoshi* (Quel-inc)

measurement frontend systemRealtime TX/RX
Error SyndromeLow-latency
feedback✓ Realtime TX/RX qubit data b/w frontend-backendImage: Comparison of the syndromeImage: Comparison of the syndrome

Subject 2: Advanced qubit control frontend

Highly-accurate signal transmission

Goal: Establish the qubit control and

 \checkmark Synchronization for scalability

Issues

- ✓ Signal quality and stability
- ✓ How to synchronize
- ✓ Efficient connection with backend
 - Low-latency feedback
 - > Optimized data scatter/gather
- ✓ Downsizing (Currently 9 U/4 qubit)
- ✓ Optimization in 300K, 70K, 3-4K, (10mK)



TX/RX timing

Current System



Subject 5: To integrate multiple RF components on a chip

socionext

Celebrating A New Milestone



Board for DC supply and temperature control System board FPGA ADC/DAC Mixer + LO Residual MW components Bandpass filters Multipliers (option) Combiners, etc.

8 channels Resolution : 16 bit Sampling rate : 12 GSPS Bandwidth: 500 MHz – 2.0 GHz Frequency: 7-11 GHz (19-22 GHz with multiplier option)

4 channels Resolution : 12 bit Receiver Sampling rate : 6 GSPS Bandwidth: 500 MHz – 2.0 GHz Frequency: 7-11 GHz

March 2023

https://www.riken.jp/pr/news/2023/20230324_1/index.html



https://pc.watch.impress.co.jp/img/pcw/docs/1488/658/html/101_o.jpg.html





Subject 3: Scalable Classical-Quantum Interface by Photonic/Cryo-CMOS Integrated Circuits

Theme 1: Exploring photonic integrated circuits operating in the extremely low-temperature environment by Prof. Shiomi

Theme 2: Development of transistor model for Si CMOS devices in the extremely low-temperature range of 4K to 70K by Prof. Shintani

Theme 3: Cryo-CMOS integrated circuits with extremely low power consumption by Prof. Sato





Subject 3 (Scalable C-Q Interface by Ph-/Cryo-CMOS ICs): Goal



Cryogenic Photonics

- Cryo optical link for qubit control
 - ✓ Operation at 10 mK region

[1] Lecocq, F., Quinlan, F., Cicak, K. *et al.* Control and readout of a superconducting qubit using a photonic link. *Nature* **591**, 575–579 (2021)

- \checkmark Optical Link for qubit controllers operating in 4 K
 - Low heat load, high speed
 - Researchers at Intel and EPFL plan to employ SiPh receivers/transmitters
- Power consuming cryo CMOS circuits needed for scalable FTQC design
 - ✓ Simplify CMOS controlling circuits to reduce power/area
 - Replace power consuming analog circuits with powerefficient optical devices



Shiomi





Circuit Cost Reduction towards Cryogenic Implementation

Issue of conventional AWG-based transmon qubit controller [1]:
 Cryo implementation is difficult due to cost of DAC and memory
 Propose a low-cost architecture (SPulseGen [2])

Related work of low-cost architecture [3]:
Target qubit is fluxonium qubits
Enable to utilize low-cost circuit
(Target of SPulseGen: Transmon qubits)

Fluxonium qubits:

Advantage: Low resonant frequency and large anharmonicityDisadvantage: Low scalability and low connectivity



[1] D.J.Frank, et al. "A Cryo-CMOS Low-Power Semi-Autonomous Qubit State Controller in 14nm FinFET Technology," ISSCC, 2022.

[2] R. Matsuo, et al. "SPulseGen: Succinct pulse generator architecture maximizing gate fidelity for superconducting quantum computers," *arXiv*, URL: <u>https://arxiv.org/abs/2312.08699</u>.

[3] L. L. Guevel, et al. "A 22 nm FD SOI < 1.2 mW/active qubit AWG free cryo CMOS controller for fluxonium qubits," ISSCC, 2024

Circuit Cost Reduction towards Cryogenic Implementation



Reduce the power consumption and area

•Memory capacity Reduced by three orders of magnitude

Increase the type of available pulses, which enables to compensate qubit variation and reduce quantum circuit depth

 \bigcirc Gate fidelity simulation:

•2-qubit gate fidelity is comparable with AWG-based architectures considering other error source in practical circuits

O To do: Replace power consuming parts (analog circuits) with optical devices. For example, PLL output signals is generated as optical signals. The signals are then fed from the room temperature region to cryogenic region.

Cryogenic Compact Modeling

- Tr. model from fab: -40℃ +125℃
- Still under development
 - ✓ Extremely low temperature at 4K
 - ✓ Extremely small technology node below 22 nm
 - Unknown physical mechanism

• Focus on only drain current

- Esp., mobility, threshold voltage, and subthreshold slope
- ✓ Even the core characteristic, only I-V, no C-V ¹⁰⁰

• No temperature scaling

- \checkmark Fit to only specific temperatures, e.g., 4K
- ✓ Assume no modulation due to self-heating
- Most critical for Cryo-VLSI design because of limited power budget



[IEEE J. Electron Devices Soc. 2018]



Characteristics to be considered as transistor model

L = 60 nm

W = 200nm

 $V_{\rm ds}$ [V]

/_{ds} [µA]

Approaches

- Our objective: Develop device-physics-based transistor model
 - ✓ Measure and model C-V @ Cryogenic temperatures
 - Clarify and model leakage current characteristics, which is essential for power prediction
 - Develop unified model that can account for room-to-cryogenic temperatures using device-physics and machine learning

Current status and future prospects

- Characterizing and modeling via the measurement of transistor array cd TEG
- Extending HiSIM (most physically sound model) considering cryogenic temperatures with Kioxia Corporation
 - <u>https://www.kioxia.com/ja-jp/about/news/2024/20240517-1.html</u>
 - <u>https://www.kit.ac.jp/2024/05/news240517/</u>



Cryogenic measurement system



Prof. Shintani, Prof. Tanaka and Prof. Navarro

Existing work of Cryogenic Circuit Architecture

Memory elements

- ✓ 28nm 2T Gain Cell embedded Dynamic RAM (eDRAM) operated at 4K [JSSCL2021]
- ✓ 65nm Mixed-2T Gain Cell eDRAM [TVLSI2021]
- ✓ 40nm 4T Gain Cell eDRAM [ISCAS2023]

Logic gates

✓ Dynamic logic exhibit 53% power efficiency improvement compared to CMOS [TCAS2024]

Processor microarchitecture design





Moonshot Goal 6 "Quantum computer" by Kobayashi PM

Dynamic Circuits at Cryogenic Temp.

- Design methodologies at cryogenic temp. is unexplored
 - Dynamic logic gates and microarchitectures are being studied intensively, however
 methodology of compiling primitives to build a larger scale circuits has yet to be established
 hardware-software co-design for cryo environment is also important
- Our objective: design technology bridging primitives, architecture, and software
 - ✓ modeling for primitive circuits

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- ✓ P&R that minimizes dynamic power
- ✓ processor-middleware considering cryo. operation
- Current status and future prospects
 - characterization and modeling via the design and measurement of primitive circuits
 - ✓ in plan: cryo-oriented P&R and compiler



Dynamic DFF w/o clkb





Subject 4: Cryo CMOS ASICs for Frontend/backend

Theme 1: Digital circuit implementation and reliability enhancement techniques by Prof. Kobayashi Theme 2: RF frontend circuit by Prof. Tsuchiya Theme 3: High-speed DAC for frontend by Prof. Takai Theme 4:High speed ADC for frontend by Prof. Miyahara Theme 5: RTL design of digital circuits for frontend by Prof. Imagawa Theme 6: Layout design of digital circuits for frontend by Prof. Kishida















Subject 4: Cryo CMOS ASICs for Frontend/backend

- Goal: To implement ASICs operating at a cryogenic temperature to control qubits (Frontend) and to correct errors (Backend)
- Research items
 - Digital circuit implementation and reliability enhancement techniques (Prof. Kobayashi, Prof. Kishida, Prof. Imagawa)
 - ✓ RF frontend circuit (Prof. Tsuchiya)
 - ✓ High-speed DAC for frontend (Prof. Takai)
 - High speed ADC for front end (Prof. Miyahara)



2024/9/12

Research Trend: RF frontend

Around 2020:

Full-integration was reported 2021 [Intel/TU Delft, ISSCC2021][Google, ISSCC2023] Basic architecture and challenges [Google, IEEE J. Microwaves 2021]

Cooling capacity of fridge (4 K stage): 1 - 2 W Target: 1 mW/qubit for 1,000 qubits

Improved architectures

Phase-shifter base [Tshinghua U., ISSCC2024] 10 mW/qubit Memory-less AWG [POSTECH, ISSCC2023] 10 mW/qubit

With new qubits, qubit-specific RF font-end architecture

AWG-less with fluxonium qubit [Google, ISSCC2024] 1.2 mW/qubit

frontend architecture development considering qubit is needed (Fig

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Tolerant against error
→ simplified RF pulse
(Fig. [Google, ISSCC2024])

Cryo DAC Research Trends

- Current steering DACs are the mainstream (RF)
- Unit current is designed to be small (650 nA) and output current is amplified by current mirror to control Qubit.
 (Ex. 10bit 650nA×1024 = 665.6µA)



- 10-bit resolution for RF applications, 14 to 20 bits for bias control
- Mostly used at 1GS/s to 2.5GS/s for RF applications.

Y. Guo et. al," A Polar-Modulation-Based Cryogenic Transmon Qubit State Controller in 28 nm Bulk CMOS for Superconducting Quantum Computing," IEEE J-SCC, VOL. 58, NO. 11, NOV. 2023

Specifications		This work	ISSCC'22 [23]	ISSCC'21 [19]	ISSCC'20 [18]	ISSCC'23 [22]	ISSCC'22 [21]	ISSCC'23 [17]	ISSCC'19 [16]
Operating 1	Temperature	3.5K	ЗК	4K	ЗК	3.5K	3.5K	ЗK	ЗК
Qubit Platform		Transmon	Transmons	Spin Qubits	Transmons & Spin Qubits	Transmon	Transmon	Transmon	Transmon
Techi	nology	28nm Bulk CMOS	14nm FinFET CCMOS	22nm FinFET CMOS	22nm FinFET CMOS	40nm Bulk CMOS	40nm Bulk CMOS	28nm Bulk CMOS	28nm Bulk CMOS
Architecture		Polar	I/Q SSB	I/Q SSB	I/Q SSB	I/Q SSB	I/Q SSB	I/Q Direct Conversion	I/Q Direct Conversion
RF Freq. Range		4-6GHz	4.5-5.5GHz	11-17GHz	2-20GHz	5-6.5GHz & 7-8GHz	4.5-8GHz	4-8GHz	4-8GHz
DAC/DPA Speed		Up to 2GS/s	1GS/s	Up to 2.5GS/s	1GS/s	Up to 2GS/s	Up to 2GS/s	1GS/s	1GS/s
DAC/DPA Resolution		10bits	10bits	10bits	10bits	10bits	10bits	10bits	N/A
SNR/SFDR		>40dB	^g ∼49dB	N/A	45dB	⁹ ~45dB	⁹ ~42dB	N/A	N/A
Data Bandwidth		N/A	N/A	Up to 2GHz	1GHz	N/A	N/A	N/A	N/A
Output Power		>-15dBm	-16dBm	-10dBm	-17.5dBm	-20dBm	-17dBm	N/A	N/A
On-chip LO	On-chip LO Generation		No, Off-chip	No, Off-chip	No, Off-chip	Yes, PLL	Yes, PLL	No, Off-chip	No, Off-chip
Z-Path Pow	ver/Channel	0~7.5mW	N/A	*2.9mW	N/A	N/A	0-10mW	°0.4mW	N/A
	Analog	[▶] 3.9mW	12.7mW	▶83mW	54mW	⁵6.7mW	⁰7.8mW	°1.9mW	2mW
XY-Path Power	Digital	2.4mW @ 1GHz	10.4mW @ 1GHz	10-140mW @ 1.6GHz	330mW @ 1GHz	12.4mW	3.8mW @ 1.25GHz	°2.3mW	N/A
/Channel	LO	₫7.4mW	N/A	N/A	N/A	N/A	12.5mW	N/A	N/A
	Total	13.7mW	23.1mW	93-223mW	384mW	19.1mW	24.1mW	°4.2mW	°2mW
Wavefo	rm Type	Arbitrary	Arbitrary	Arbitrary	Arbitrary	Rect./Raised cosine	Rect./Raised cosine	Cosine	Symmetric pulse
Target	Fidelity	99.9%	99.99%	99.99%	99.99%	99.99%	N/A	99.99%	99.99%
DRAG Pulse	DRAG Pulse Generation		Yes	No	No	Yes	No	Yes	No
¹ Chip Are	a/Channel	0.9mm ²	f1.61mm ²	f4mm ²	4mm ²	1.04mm ²	f1.3mm ²	3.5mm ²	1.6mm ²
² Power/qubit cor	t under active htrol	^h 13.7mW/qubit (w/ LO)	23.1mW/qubit (w/o LO)	⁷ 3-7mW/qubit (w/o LO)	[/] 12mW/qubit (w/o LO)	19.1mW/qubit (w/o LO)	24.1mW/qubit (w/ LO)	°4.2mW/qubit (w/o LO)	°2mW/qubit (w/o LO)

¹ The chip area includes the area of analog, digital and LO.

² The power is the total power of one channel including analog, digital and LO (if integrated on-chip). ^a Gate pulsing for spin qubits.
^b Tested with continuous output at max. output power.

⁶ The power is the average power with a non-continuous quantum gate operation.

^d Including the power of the clock generator and LO buffer.

^o This IC only generates 16 types of fixed length symmetric driving pulse.

¹ Estimated from the chip microphotographs.

⁹ Estimated from the relative measurement results.

^h The power consumption of a 500 MHz external reference is not included.
ⁱ The power consumption is calculated for 32 time-frequency multiplexed qubits under active control

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Cryo ADC Research Trends

- Interleaved SAR ADCs are the mainstream
- $F_s < 1GS/s$, ENOB = 6 \sim 9bit

This is due to significant power consumption constraints and the difficulty of making high-precision measurements.



2x Interleaving SAR ADC [4]

Ref	Fs (MS/s)	SNDR (dB)	Power (mW)	FoMw (fJ/cs.)	FoMs (dB)
[1]	250	57.9	24.7	154	154.9
[2]	500	50.1	5.91	45.1	156.4
[3]	1000	41.1	1.94	20.9	155.2
[4]	1000	36.2	10.6	100	142.9
[5]	1000	38.7	1.79	25.4	153.2



Digital Circuit Implementation

Kobayashi Imagawa Kishida

• For frontend

- ✓ Migrate FPGA-based design by Quel (Miyoshi) to ASIC
 - Not easy-going. Synchronous reset on FPGA vs Asynchronous reset on ASIC. IP on FPGAs must be replaced by random logics.
 For 4 gubit Power
 - > LVDS interface from qubit by Prof. Miyahara



For 4 qubitPowerClock Network575 mWMemory156 mWOthers17 mWTotal748 mW

		Power	Area
Kyushu-U's	180um	130 mW	6.83mm ²
Our Impl.	180um	25 mW	1.87mm ²
	22nm	685 μW	0.0163mm ²

• For backend

 ✓ A greedy error correction decoder to ASIC Smaller area and power than Kyushu-U's [Nakamura et. al, 2023/03 ARC-252]

RF Frontend

Mission 1: Cryo-RF Device model (-2025)

Cryo-RF device model is essential for future circuit design Current status: Numerical evaluation [SPI2024] Measurement in progress Resistance of thinner wires are still high at 4K

Mission 2: Scalable RF frontend by Cryo-CMOS

Cryo-RF circuit design including PLL and mixer **Current status**: 1st test chip (PLL) in under measurement 2024-2025: PLL and mixer design (2024), Integration in a frontend ASIC (2025) Milestone (-2030): Scalable RF frontend architecture **Current status**: Survey and discussion with Subject 3 -2030: Propose scalable frontend/qubit architecture



Numerical model of size-dependent ρ [IEEE SPI2024]

Chip for device modeling



High-speed low-power DAC

- Goal: Automatic design of High-speed DAC operating at a cryogenic temperature.
- Backgroud & Challenges
 - Automatic design can vary parameters in the circuit more broadly than human design
 - Simulation of a DAC is time consuming, making it impractical to calculate rewards from simulation results of a DAC.
 - ✓ DAC consists of many identical circuits whose scale is small, so the simulation time of the identical circuit can be shortter.

Results & Future Works

- ✓ Automatic design program achieved a DAC with a power consumption of 4.35 mW and SFDR of 94.4dB in an execution time of 1,058 seconds.
- Automatic design of a DAC using CMOSFET parameters compatible with a cryogenic temperature..





Scheme of 12bit DAC



Element Circuit of 12bit DAC

Theme 4: High-speed ADC

• Goal

- Development of a scalable Cryo ADC
 - ≻ Resolution \sim 12bit
 - > Sampling rate \sim 6GS/s



Miyahara

Challenges

- Development of scalable ADC architecture suitable for interleaved operation
- Development of calibration techniques for channel-to-channel mismatches with flexibility

• Current Status

- Successfully design and evaluated of a high-speed, low-power single Cryo ADC using 22nm bulk CMOS
- Currently designing an interleaved ADC aiming for 2GS/s operation



10bit, 300MS/s, 2.5mW @4.2K

Agenda

Self Introduction

Introduction



Quantum Bit Error Correction System

Moonshot Goal 6

- ✓ Moonshot Goal 6 for quantum computers
- Integrated circuits (Classical electronics) and quantum computers

QUBECS

Overview of my project for developing an FTQC (Fault-tolerant quantum computer)

Conclusion



Conclusion

• Classical electronics (semiconductor chips) must be used to develop an FTQC

- \checkmark To control qubits and correct errors
- ✓ Current advances of Si-based integrated circuits are not based on Moore's law. High-cost and power-hungry \rightarrow QC may be a help
- Fidelity and Scalability of qubits are insufficient to develop an FTQC
 - ✓ Reliability, Reproducibility, and Mass-productivity must be incorporated

• QUBECS in the Moonshot Goal 6

- ✓ 14 PIs mainly for classical electronics. No quantum physicists
- \checkmark Theme 1 for error correction by using FPGA cluster
- ✓ Theme 2 & 5 for a qubit controller at room temperature
- Theme 3 & 4 for integrated and optical circuits working at cryogenic temperature to control qubits and correct errors

Thank you!



QUBECS

Quantum Bit Error Correction System Moonshot Goal 6

• Question or comment



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